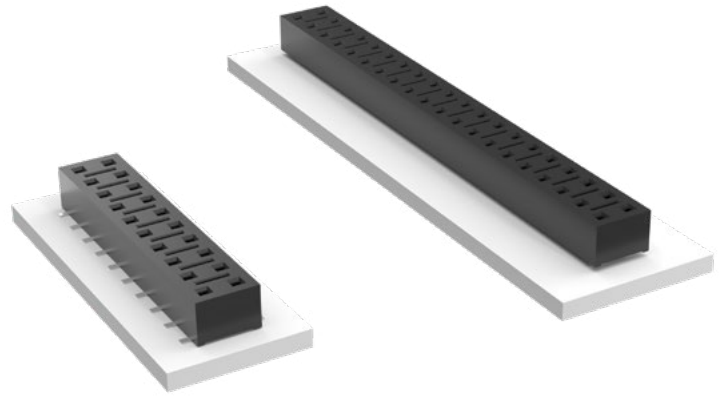# TIGER BEAM™ CONTACT

COST-EFFECTIVE RELIABLE SOCKET

(2.54 mm) .100" PITCH • HLE SERIES

HLE
Board Mates:
TSW, MTSW, DW, EW,
ZW, TLW, TSM, MTLW, HW

SPECIFICATIONS

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating (HLE/TSM):
4.1 A per pin
(2 pins powered)
Voltage Rating:
400 VAC
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.78 mm) .070" to
(3.43 mm) .135" pass-through,
or (2.59 mm) .102" min
plus board thickness for
bottom entry

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-20)
(0.15 mm) .006" max (21-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

ALSO AVAILABLE
MOQ Required

Other Platings

Note:
Some lengths, styles and
options are non-standard,
non-returnable.

HLE	–	1	NO. PINS PER ROW	–	02	–	PLATING OPTION	–	DV	–	TAIL OPTION	–	OTHER OPTION

02 thru 50

PLATING OPTION

–F
= Gold flash on
contact,
Matte Tin on tail

–L
= 10 µ" (0.25 µm)
Gold on contact,
Matte Tin on tail

TAIL OPTION

Leave blank for
Surface Mount
(Requires –BE for
Bottom Entry)

–TE
= Through-hole
Top Entry

–PE
= Through-hole
Pass-through
Entry
(Requires –BE for
Bottom Entry)

OTHER OPTION

–BE
= Bottom Entry
(Not available
with –TE)

–A
= Alignment Pin
(4 positions min.)
Metal or plastic at
Samtec discretion
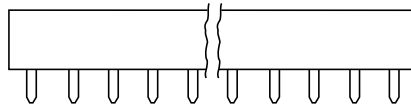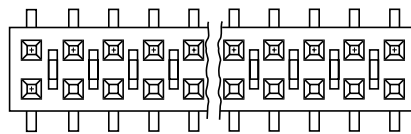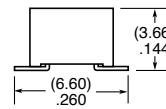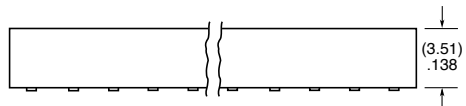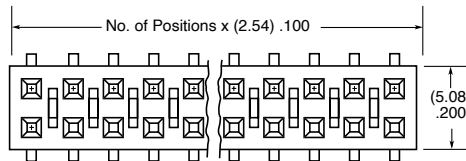(Not available with
-TE, -PE & -LC)

–LC
= Locking Clip
(2 positions min.)
(Not available with -A)
(Manual placement
required)

–K
= (6.50 mm)
.256" DIA
Polyimide Film
Pick & Place Pad
(3 positions min.)
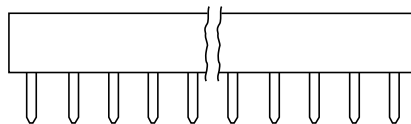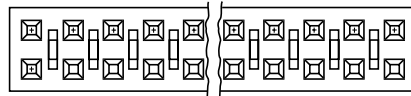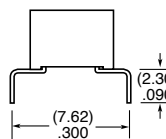Not available
with –TE or
–PE tail option

–P
= Metal Pick
& Place Pad
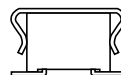(3 positions min.)

–TR
= Tape & Reel
(29 positions max.)

–FR
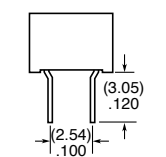= Full Reel
Tape & Reel
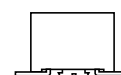(must order max.
quantity per reel;
contact Samtec for
quantity breaks)

No. of Positions x (2.54) .100

(5.08) .200

(3.51) .138

(3.66) .144

(6.60) .260

–PE

(2.30) .090

(7.62) .300

–TE

(3.05) .120

(2.54) .100

–P

–LC

–A

samtec.com?HLE